

AR9000W

12 英寸精密自动划片机 (WAFER)

- 最大有效加工尺寸 (mm)

Ø12"

- 主轴配置方式

对向式双主轴



• 特点 FEATURE

高速料盒框架扫描，防撞报警，高速传输定位，状态纠错能力强。

High-speed cassette frame scan, anti-collision alarm, high-speed transmission position, and strong status error correction capability.

全自动上下料、自动传输定位、自动对准切割、自动刀痕检测，降低 OP 工作量。

Fully automatic load and unload, automatic transmission and position, automatic alignment cut, automatic kerf check, reduce OP workload.

主轴对装龙门工作台结构，双刀间距最小 28mm，双轴切割工艺适应范围更广。

Spindle to gantry table structure, double spindle spacing minimum 28mm, dual-spindle cutting process to adapt to a wider range.

优化双轴高效切割模式，效率较单机提高约 80%。

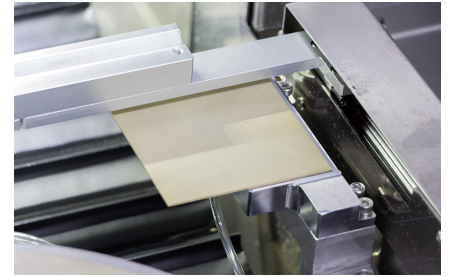
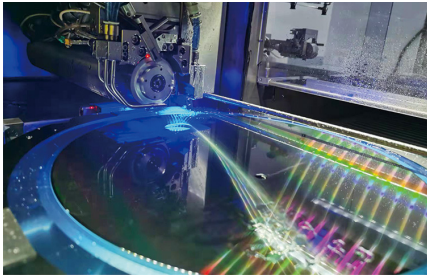
Optimized dual-spindle high-efficiency cutting mode, efficiency increased by about 80% compared to single equipment.

精密进口滚珠丝杆、直线导轨，Y 向光栅尺闭环控制，高精度机台长时间保持。

Precision imported ball screw, linear guide, Y-directional scale closed-loop control, high-precision machine to maintain a long time.

相较旧款 UPH 提高 10%

UPH (Units Per Hour) has been increased by 10%.



功能 FUNCTION

注: 「*」为选配功能, 支持个性化定制
PS: 「*」 is an optional feature that can be customized by the customer

高精度非接触式测高

High-precision non-contact setup

多片同盘双刀切割

Chips dicing in the same time with dual-spindle

故障自纠错功能, 多种位置实施检测

Fault self-correcting function, a variety of locations to implement the detection

自动校准、自动刀痕检测、刀片破损检测系统

Automatic calibration & Automatic kerf check & Blade breakage detection

适应不同工艺, 可选多种自动对准算法

Adapt to different processes with a variety of auto-alignment algorithms

首片切后检验功能

First post-cut inspection function

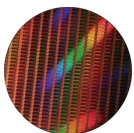
* 工厂自动化模块

Factory Automation Module

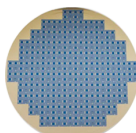
参数 PARAMETER

工作尺寸		Φ8", Φ12"
主轴		双轴 1.2/1.8/2.4/3.0 kW 最大 60000 rpm
刀片尺寸		2"
Y1 / Y2 轴	单步步进量 到位精度 切割范围	0.0001 mm < 0.002 mm 310 mm
X 轴	进刀速度输入范围	0.1-600 mm/s
Z1 / Z2 轴	单步步进量 到位精度	0.0001 mm ≤ 0.001 mm
θ 轴	到位精度	±15 °
清洗台	旋转速度 清洗方式	100-3000 rpm 全自动冲洗并甩干
工作电压		三相 380V 50Hz
设备信息	长宽高 WxDxH 重量	1550x1255x1880 mm 2100 Kg

应用 APPLICATION



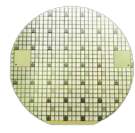
硅晶圆



砷化镓



钽酸锂 / 铌酸锂



SiC